

Optical Wafer Thickness MicroGauge

TM5300-6

FIBERPRO released Optical Wafer Thickness MicroGauge (TM5300-6) which is of great use in measurement of Thickness, TTV, LTV,

Warp and Bow of various Si wafers, Sapphire wafers, Glass wafers, and light-reflected materials. It can be designed under In-line / Off-line measurement condition with motion stage controller in various applications. There will be no physical damage on the samples during measurement, and it can be protected from dust or pollutant by having a cover.

As TM5300-6 is compact and portable, it is easy to move for measurement.

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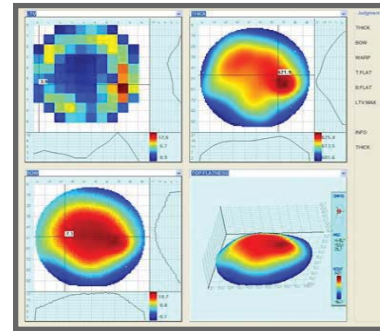


Features

- Compact designable size
- Up to 6" Wafer measurement
- High Accuracy & Repeatability
- No Calibration needed
- User friendly operating program (LTV, 3D)
- High speed measurement (500Hz for Warp / 1kHz for Thickness)
- Thickness / Warp / Bow / LTV / TTV / Stress measurement

Applications

- Si Wafer / Sapphire Wafer / Glass Wafer / SiO₂ / GaAs material manufacturing process
- Etch / Grinder Process Control
- Metrology Industries
- Wafer Thinning Process
- Thickness / Warp / Bow / LTV / TTV / Flatness Stress Measurement & Analysis



4 inch Silicon Wafer measurement

Specifications

Thickness	
Accuracy ¹⁾	0.2um
Repeatability	0.1um
Range ³⁾	100um ~ 2,000um
Warp / Bow / Flatness	
Accuracy ¹⁾	0.5um
Repeatability	0.2um
Range	200um
System	
Maximum Size of Wafer	≤ 6 inch (150mm)
Measurement time	< 100sec ²⁾
Remote Interface	TCP/IP
Power	Input : 100 ~ 240VAC (50 / 60Hz) Consumption : 260VA
Dimensions (W x D x H)	380mm x 370mm x 380mm
Weight	About 26kg

- 1) Accurate refractive index of sample must be known.
- 2) Based on the measurement of 10,000 points for 100mm wafer.
Number of measurement points and range can be customized.
- 3) Be different in accordance with material's refractive index.